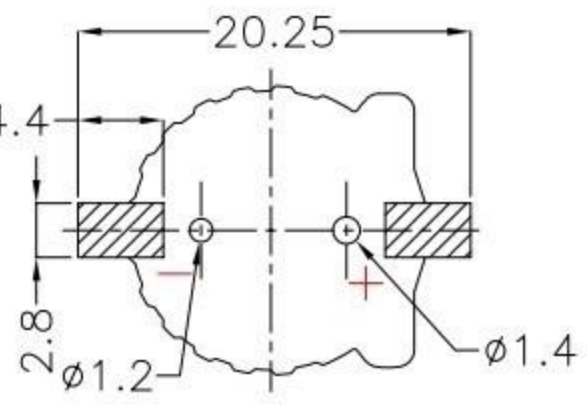
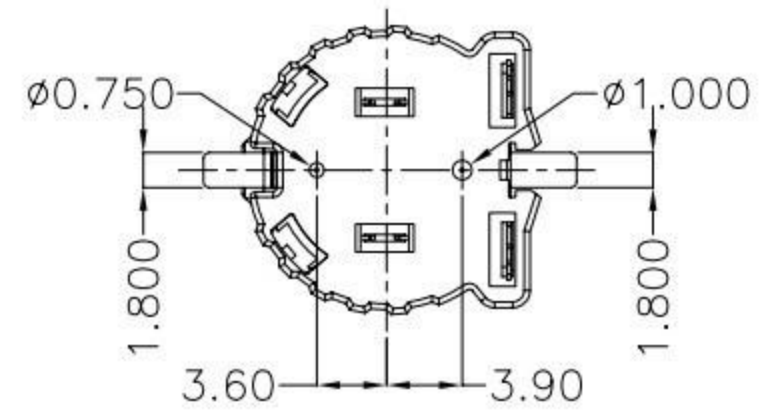
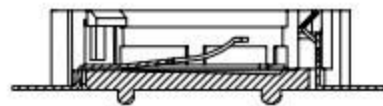
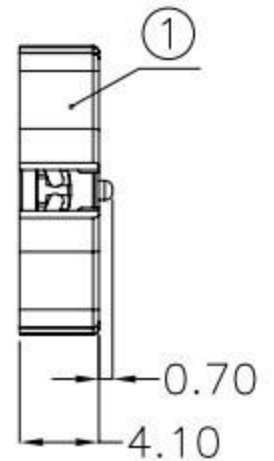
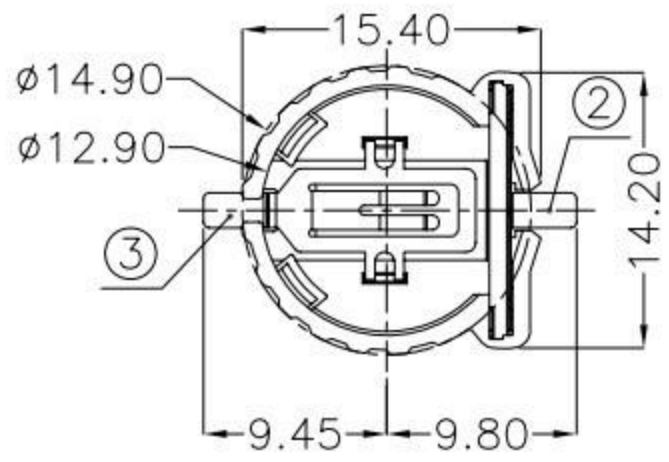




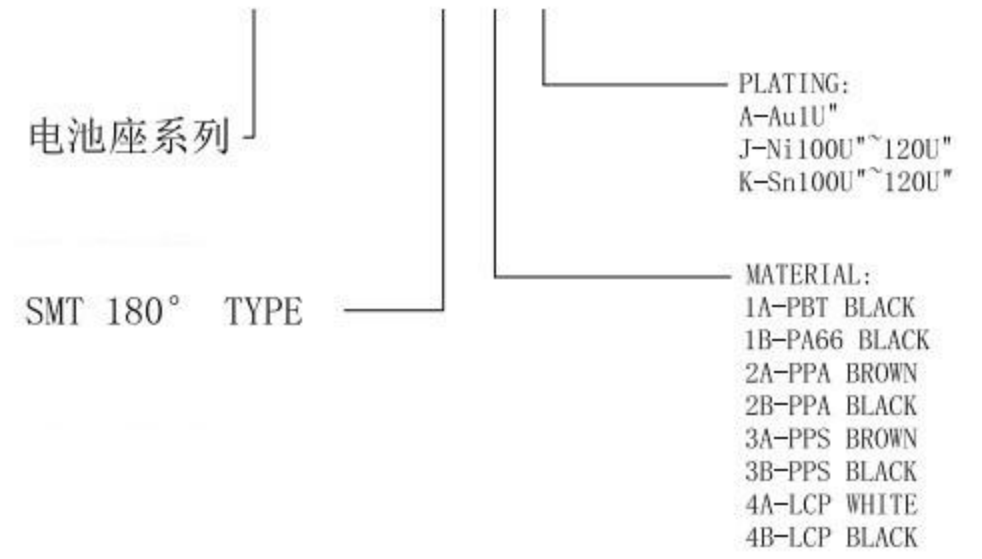
REV.	ECN NO.	REVISED	DATE



PCB Layout Diagram
Top View

- 1.MATERIAL:
a.HOUSING:PPA
b.CONTACT:PHOSPHOR BRONZE
(SURFACE PLATING: Au1u")
SEE ORDERING INFORMATION
- 2.ELECTRIC:
a.CONTACT RESISTANCE: 30 MILLIOHMS MAX
b.INSULATION RESISTANCE: 1000 MEGA OHMS MIN
c.DIELECTNIC VOLTAGE: 500V AC ONE SEC LEVEL
d.OPERATING TEMPERATURE: -25°C~ +85°C

ORDERING INFORMATION



3	TERMINAL(-)	1	PHOSPHOR BRONZE, T=0.20mm	Gold Plating and Ni Under-Plating
2	TERMINAL(+)	1	PHOSPHOR BRONZE, T=0.20mm	Gold Plating and Ni Under-Plating
1	HOUSING	1	PPA	BROWN
NO.	PART NAME	Q'TY	MATERIAL	PLATING & COLOR

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS: X: ±0.30, X.X: ±0.25, X.XX: ±0.20, X.XXX: ±0.10
ANGLES: X: ±1°, X.X: ±0.5°

廣東科斯達電子科技有限公司

DSND	DATE	2017-07-13	TITLE:
CHKD	DATE	2017-07-13	
APVD	DATE	2017-07-13	PART NO.:
WEIGHT: 1.91g	SCALE: 2:1	SIZE: A4	VIEW:
SHEET 1 OF 1	UNIT: mm	REV.: A/0	OBJECT: MY
			DRAW NO.: